

Ultra-Low Capacitance TVS Diode

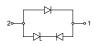
- ESD / transient protection of high-speed data lines exceeding IEC61000-4-2 (ESD): ±20 kV (air / contact) IEC61000-4-4 (EFT): 2.5 kV/50 A (5/50 ns) IEC61000-4-5 (surge): 3 A (8/20 μs)
- Extremely small form factor down to 0.62 x 0.32 x 0.31 mm³
- Max. working voltage: 3.3 V
- Very low reverse current: < 1 nA typ.
- Extremely low capacitance: 0.4 pF typ.
- Very low clamping voltage: 12 V typ. at positive transients, 4 V typ. at negative transients
- Very low series inductance down to 0.2 nH typ.
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101

Applications

- USB 2.0, 10/100/1000 Ethernet, Firewire, DVI, HDMI, S-ATA
- Mobile communication
- Consumer products (STB, MP3, DVD, DSC...)
- LCD displays, camera
- Notebooks and desktop computers, peripherals



ESD3V3U1U-02LS ESD3V3U1U-02LRH



Туре	Package	Configuration	Marking
ESD3V3U1U-02LRH	TSLP-2-7	1 line, uni-directional	E3
ESD3V3U1U-02LS	TSSLP-2-1	1 line, uni-directional	Z





Maximum Ratings at $T_A = 25^{\circ}$ C, unless otherwise specified

Parameter	Symbol	Value	Unit
ESD (air / contact) discharge ¹⁾	V _{ESD}	20	kV
Peak pulse current ($t_p = 8 / 20 \ \mu s$) ²⁾	I _{pp}	3	A
Operating temperature range	T _{op}	-55125	°C
Storage temperature	T _{stg}	-65150	

Electrical Characteristics at $T_A = 25^{\circ}$ C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics				_	
Reverse working voltage	V _{RWM}	-	-	3.3	V
Breakdown voltage	V _(BR)	5	-	-	
I _(BR) = 1 mA, from pin 1 to 2					
Reverse current	I _R	-	< 1	50	nA
$V_{\rm R}$ = 3.3 V, from pin 1 to 2					
Clamping voltage	V _{CL}				V
$I_{\rm PP}$ = 1 A, $t_{\rm p}$ = 8/20 µs ²⁾ , from pin 1 to 2		-	10	13	
$I_{\rm PP}$ = 3 A, $t_{\rm p}$ = 8/20 µs ²⁾ , from pin 1 to 2		-	12	15	
Forward clamping voltage	V _{FC}				
$I_{\rm PP}$ = 1 A, $t_{\rm p}$ = 8/20 µs ²⁾ , from pin 2 to 1		-	2	4	
$I_{\rm PP}$ = 3 A, $t_{\rm p}$ = 8/20 µs ²⁾ , from pin 2 to 1		-	4	6	
Line capacitance ³⁾	CT	-	0.4	0.6	pF
$V_{R} = 0 V, f = 1 MHz$					
Series inductance	L _S				nH
ESD3V3U1U-02LS		-	0.2	-	
ESD3V3U1U-02LRH		-	0.4	-	

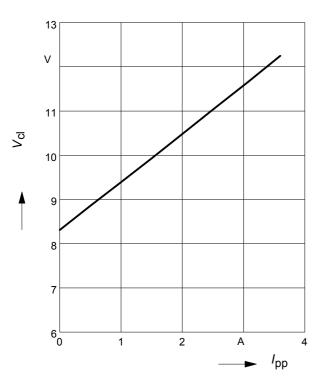
 $^{1}V_{\text{ESD}}$ according to IEC61000-4-2

 $^2\textit{I}_{pp}$ according to IEC61000-4-5

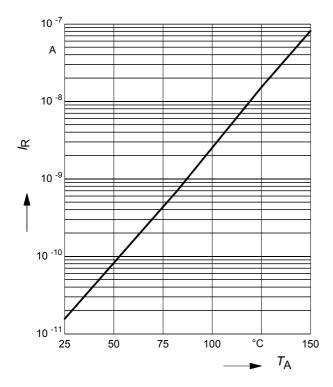
³Total capacitance line to ground



Clamping voltage, $V_{cl} = f(I_{pp})$ $t_p = 8 / 20 \ \mu s$, from pin 1 to 2

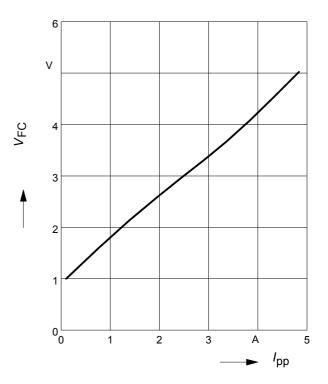


Reverse current $I_{R} = f(T_{A})$ $V_{R} = 3.3$ V, from pin 1 to 2

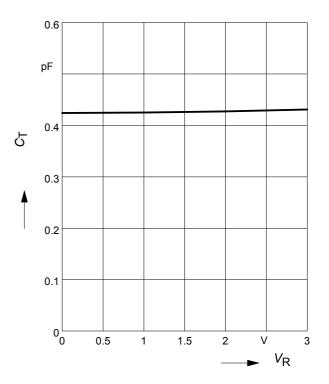


Forward clamping voltage $V_{FC} = f(I_{PP})$

 $t_{\rm p}$ = 8 / 20 µs, from pin 2 to 1



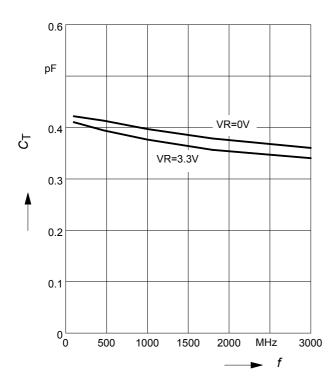
Line capacitance $C_T = f(V_R)$ f = 1 MHz, from pin 1 to 2





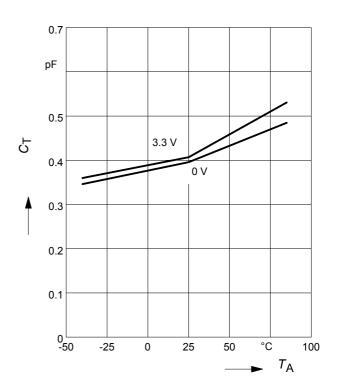
Line capacitance $C_T = f$ (f)

 $V_{\rm R}$ = parameter, from pin 1 to 2



Line capacitance $C_{T} = f(T_{A})$

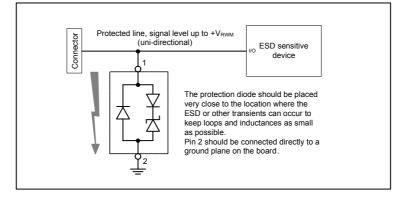
 $V_{\rm R}$ = 0 V, *f* = 1 MHz



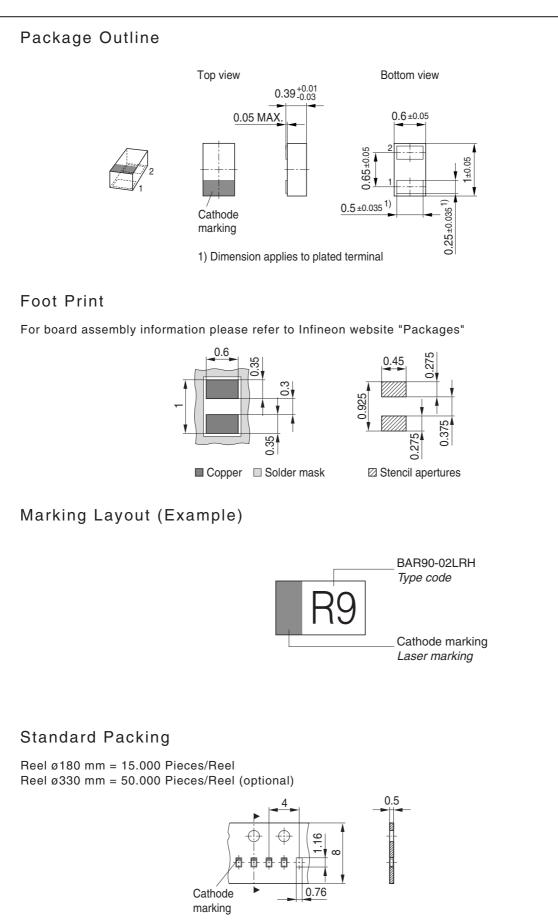


Application example ESD3V3U1U...

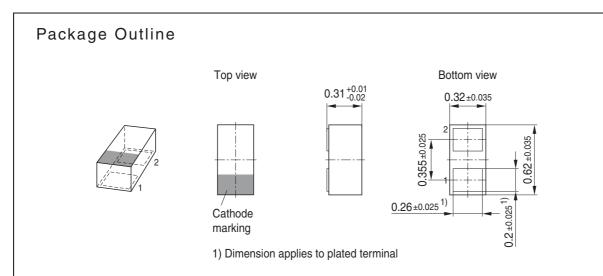
1-channel, uni-directional





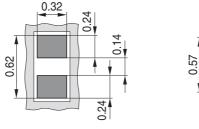


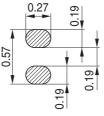




Foot Print

For board assembly information please refer to Infineon website "Packages"

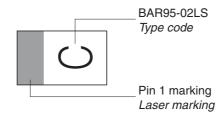




Copper Solder mask

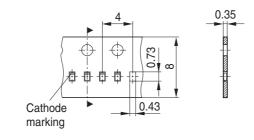
Stencil apertures

Marking Layout



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel





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